

ABSTRACT

Provided is an electroplating apparatus and an electroplating method. The electroplating apparatus comprises an electroplating chamber (100), a wafer holding device (200), a stirring mechanism (300), and a driving mechanism (400). The stirring mechanism (300) is arranged in the electroplating chamber (100), when the wafer holding device (200) holds a wafer, the stirring mechanism (300) is provided parallel to the wafer. The driving mechanism (400) is configured to drive the stirring mechanism (300) to perform continuous main-periodic reciprocating motions parallel to the wafer, so that the stirring mechanism (300) stirs an electroplating solution. Wherein, each main-periodic reciprocating motion comprises N continuous sub-periodic reciprocating motions, and N is an integer greater than or equal to 2. Within the same main period, the ending position of the previous sub-period is the starting position of the subsequent adjacent sub-period, the sub-stroke in the same sub-period is a real number greater than 0, and the sub-stroke is the distance between the ending position and the starting position in the same sub-period. In the present invention, by regulating the motion mode of the stirring mechanism, the electroplating efficiency is improved, and the effect of uniform electroplating is achieved at the same time.